

☆TDK Multilayer Ceramic Chip Capacitors

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Creation Date: July 31, 2014

C1608X5R1A335K080AC (TDK item description: C1608X5R1A335KT****)

Applications



Commercial Grade



Please refer to Part No. CGA3E1X5R1A335K080AC for automotive use.

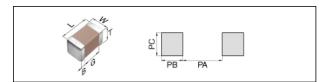
Feature

General

General (Up to 50V)

Series

C1608 [EIA CC0603]











Size	
Length(L)	1.60mm +/-0.10mm
Width(W)	0.80mm +/-0.10mm
Thickness(T)	0.80mm +/-0.10mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	0.30mm Min.
Recommended Land Pattern(PA)	0.70 to 1.00mm (Flow Soldering) br />0.60 to 0.80mm (Flow Soldering)
Recommended Land Pattern(PB)	0.80 to 1.00mm (Flow Soldering) br />0.60 to 0.80mm (I
Recommended Land Pattern(PC)	0.60 to 0.80mm (Flow Soldering) < br /> 0.60 to 0.80mm (
Recommended Slit Pattern(SD)	

Electrical Characteristics		
Capacitance	3.3uF +/-10%	
Rated Voltage	10Vdc	
Temperature Characteristic	X5R(+/-15%)	
Dissipation Factor	10% Max.	
Insulation Resistance	30MΩ Min.	

Other		
Soldering Method	Reflow, Flow	
AEC Q200	No	
Packing	Punched (Paper)Taping [180mm Reel]	
Package Quantity	4000Pcs Min.	

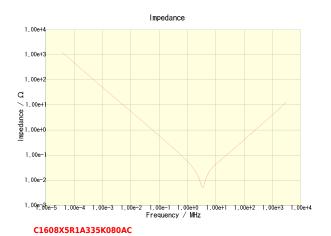
[•]This PDF document was created based on the data listed on the TDK Corporation website.

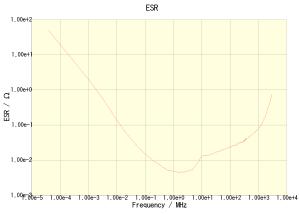
[•]All specifications are subject to change without notice.

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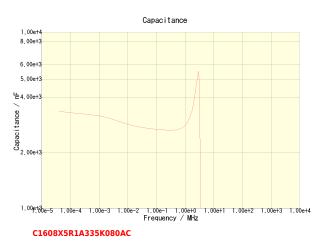
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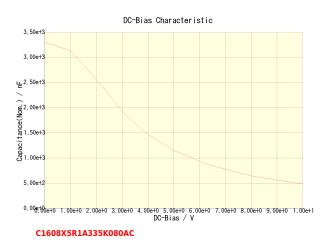
Characteristic Graphs (This is reference data, and does not guarantee the product's characteristics.)

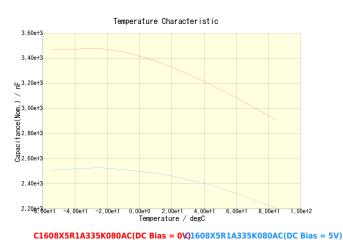


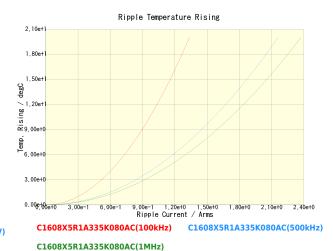


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